

C1206X100M2TACTU

Aliases (C1206X100M2TAC7800)

SMD Comm X8G HT150C Flex, Ceramic, 10 pF, 20%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm



General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	15 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1206
L	3.3mm +/-0.4mm
W	1.6mm +/-0.35mm
Т	0.78mm +/-0.20mm
S	1.5mm MIN
В	0.6mm +/-0.25mm

_	3.5Hill 7 0.4Hill	1,100
W	1.6mm +/-0.35mm	Tole
T	0.78mm +/-0.20mm	Vol
S	1.5mm MIN	Die
В	0.6mm +/-0.25mm	Ten
		Ten
Packaging Specifications		Car

	Specifications		
	Capacitance	10 pF	
	Measurement Condition	1 MHz 1.0Vrms	
	Tolerance	20%	
	Voltage DC	200 VDC	
	Dielectric Withstanding Voltage	500 VDC	
	Temperature Range	-55/+150°C	
	Temp. Coefficient	X8G	
	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms	
	Dissipation Factor	0.1% 1 MHz 1.0Vrms	
	Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours	
	Insulation Resistance	100 GOhms	

Packaging	T&R, 180mm, Plastic Tape	Reference to +25°C and 0 VDC Applied (TCC)	
Packaging Quantity	4000	Dissipation Factor	0
		Aging Rate	0

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Generated 05/04/2025 © 2006 - 2025 YAGEO